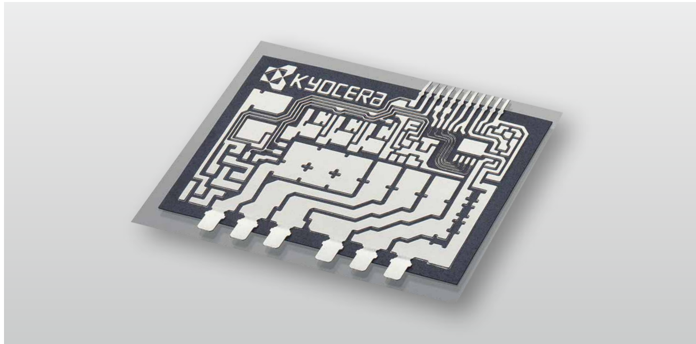
ACTIVE METAL BONDING SUBSTRATES
FOR EV/HEV INVERTERS



APPLICATIONS

- Power module devices

FEATURES

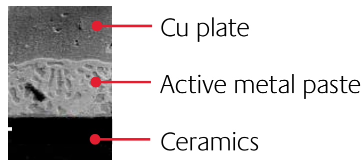
- High reliability (AMB Technology)
- Variety of platings (Ni, Ni/Au, NiPdAu, Ni/Pd/Ag, Ag)
- High thermal conductivity
- Multilayer structure feasible
- Different Cu thickness plates on same substrate
- Various connector possibilities

PLATING OPTIONS

- Partial silver plating
- Direct silver plating
- Nickel-palladium-gold or silver plating
- Nickel-gold plating
- Nickel plating

RELIABILITY AMB PROCESS

- Active Metal Bonding
- Ti Compound - alloy (Ag-Cu)
- High adhesion strength to ceramics



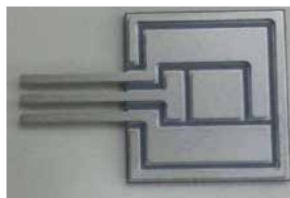
MULTILAYER STRUCTURE

Inner CU plane

- Multilayer AMB structure
- Low inductance
- 3 dimensional routing

CONNECTOR TECHNOLOGIES

Lead type


Long lead type

Cu PIN type

Screwable (SiN) type

MATERIALS AVAILABILITY

- Si_3N_4: High flexural strength (850 MPa)

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